

**APPLICATION DATA SHEET****Inventor Information**

Inventor One Given Name : Sion C.  
Family Name : QUINLAN  
Postal Address Line One : 1, Lockstile Way  
Postal Address Line Two : Goring on Thames  
City : Oxon  
Postal or Zip Code : RG8  
Country of Residence : United Kingdom  
Citizenship Country : United Kingdom

Inventor Two Given Name : Tim J.  
Family Name : BALES  
Postal Address Line One : 15 Derbyshire Green  
Postal Address Line Two : Warfield  
City : Bracknell  
Postal or Zip Code : RG42 -3TG  
Country of Residence : United Kingdom  
Citizenship Country : United Kingdom

**Correspondence Information**

Name Line One : Andrew F. Pratt, Esq.  
Address Line One : DORSEY & WHITNEY LLP  
Address Line Two : 1420 Fifth Avenue, Suite 3400  
City : Seattle  
State or Province : Washington  
Postal or Zip Code : 98101  
Telephone : 206-903-8800  
Facsimile : 206-903-8820  
E-Mail : patentseattle@dorseyllaw.com

**Application Information**

Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND  
METHOD FOR ELECTRICALLY ISOLATING MODULES  
Total Drawing Sheets : 3  
Formal Drawings : YES  
Application Type : Utility  
Attorney Docket Number : 500986.02  
Assigned : Yes (Large Entity)

**Representative Information**

Representative Customer No. : 27,076

**Prior Foreign Application**

Foreign Application One : 0126821.8  
Filing Date : November 7, 2001  
Country : United Kingdom  
Priority Claimed : Yes

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